

# RESEARCH AREA

## Research Area

- RFIC : Transceiver, LNA, PA, PLL, Mixer, VGA, Phase-Shifter, *et al.*
- Frequency: From DC to 300GHz
- Process: CMOS (TSMC 28nm, others), III-V (Wolfspeed GaN, InGaAs etc)

## Research Applications

- Mobile Wireless Communication
- High-speed Wireline Communication
- Vehicular Communication and Radar
- THz Communication



**Assoc. Professor  
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Program Director,  
RF & MM-wave,  
VIRTUS, NTU**



Web: <http://www.ntu.edu.sg/home/eccboon>

# Research Funding in Recent 5 Years

## Research Leadership in RF/MMW IC

Funding Source/ Project Title	Institute/University /Industry Partner	Role	Grant Period
Delta-NTU Corp. Lab: A Wireless Heterogeneous Network Transceiver Chipset for Content-Driven Transmission of Learning Media (SLE-RP3) Research Area (SLE)	Delta-Electronics	PI	1 <sup>st</sup> July 2016 to 30 <sup>th</sup> June 2021
MOE Tier 1: Monolithic Terahertz Passive Components in Advanced CMOS Technology: From Fundamental Understandings to Integrated Circuit Applications	MOE	PI	1 <sup>st</sup> November 2016 to 31 <sup>st</sup> October 2018
GlobalFoundries Singapore Pte. Ltd-NTU Joint R&D: Direct Integration of GaN Power Devices on CMOS Circuits for Demonstrate Power Management Solutions,	GlobalFoundries	PI	1 <sup>st</sup> June 2016 to 31 <sup>st</sup> December 2018
SMART-POC: An Integrated Platform Approach Towards Non-Invasive Continuous Blood Glucose Monitoring Addressing Clinical Need for Early Diagnosis and Improved Compliance	SMART-MIT	PI	1 <sup>st</sup> July 2016 to 30 <sup>th</sup> July 2017
Huawei Tech. Co. Ltd-NTU Joint R&D: 10GiFi research & development of ultra-wideband RF transceiver	Huawei	PI	15 <sup>th</sup> July 2014 to 14 <sup>th</sup> July 2018
Tier 2: High Thermal Resolution Ultra-Low Power Integrated Imager: Fund. Issues in CMOS	MOE	PI	July 2013 to June 2016
Electronic Circuit Design, Communications under SMART-IRG5: Low Energy Electronic Systems (MIT-NTU) (Multiple grants)	MIT	PI	1 <sup>st</sup> April 2014 to 30 <sup>th</sup> June 2021

# Projecting Funding Since 2019

Project Title	Grant Type	Amount Approved	Project Start date
CMOS Terahertz Plasmonic Interconnect towards Tera-scale Computing	AcRF Tier2	788,736.00	28-Jan-2020
Transceiver Test and Development Applicable for V2X-System and mmW	RCA	125,000.00	22-Jan-2020
Transceiver Development Applicable for Hybrid "C-V2X-System +DSRC" V2X-System	IAF-PP(AME Domain)	2,889,900.00	01-Nov-2019
LEES III-V+CMOS Circuits & System towards Commercialization	Singapore-MIT Alliance for research and Technology (SMART) Centre	364,800.00	01-July-2019

# Main Projects in Recent 5 Years

2014 – 2018 (Carrier Aggregation RF Transceiver for Next Generation WiFi)

5-6GHz 3-Carrier  
Aggregation Transceiver,  
World First Demonstrated



2016-2020 (Multi-Mode Transceiver for Smart Learning)

Sub-6GHz Transceiver:  
Support 2.4G/5GHz WiFi,  
Bluetooth, ZigBee



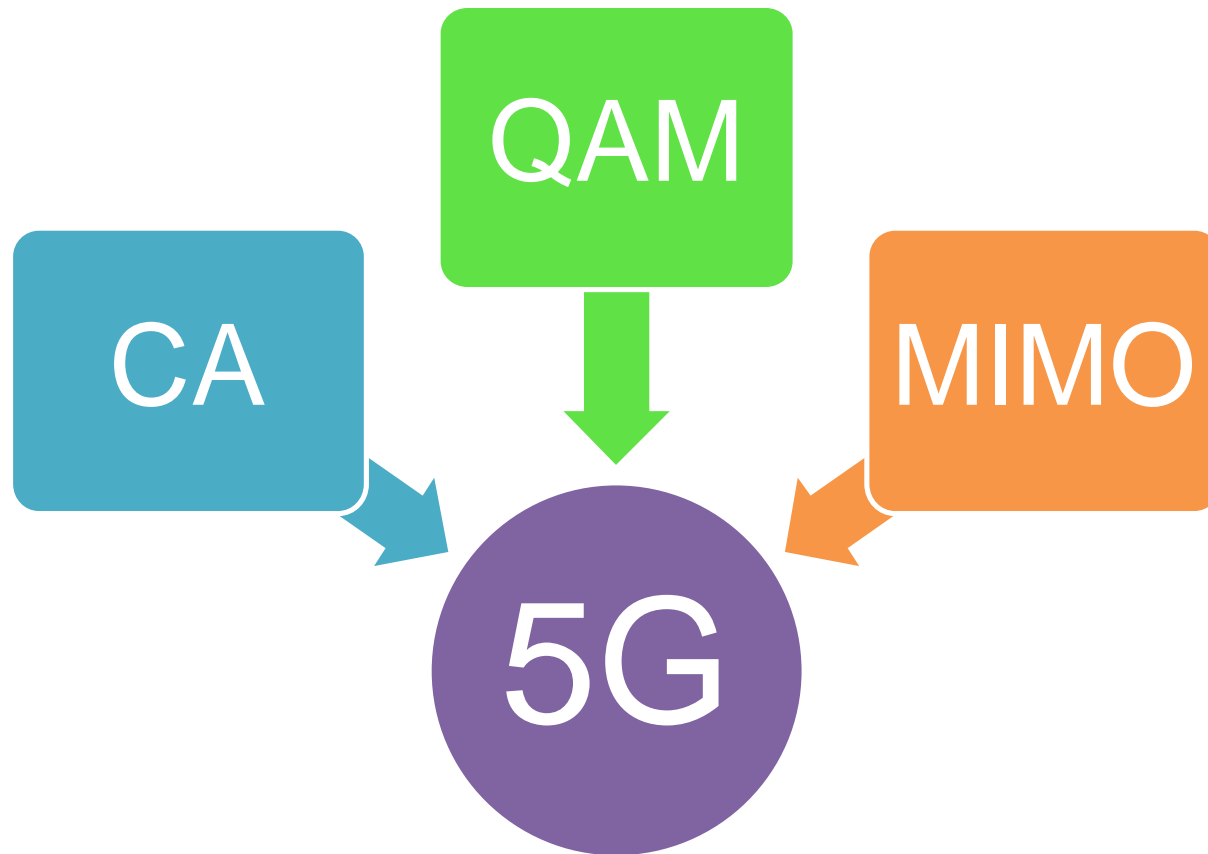
2017- (LESS: CMOS+III-V)

5G NR and 802.11ax  
Front-end :  
CMOS + GaN  
Wireless Power Transfer:  
CMOS + GaN



Singapore-MIT Alliance for Research and Technology

# 5G Key Enabling Technologies



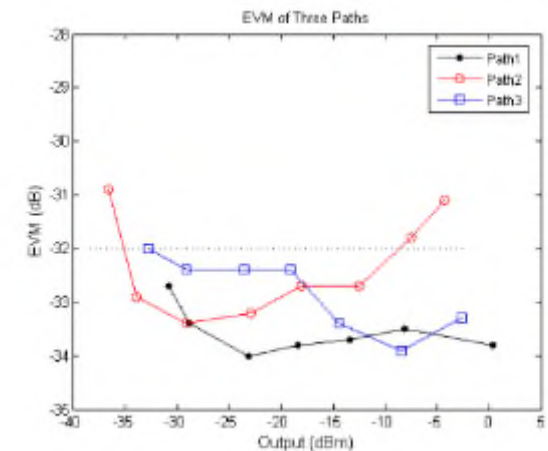
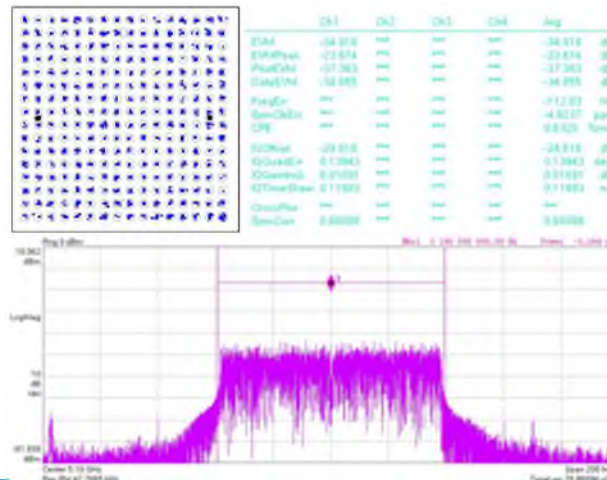
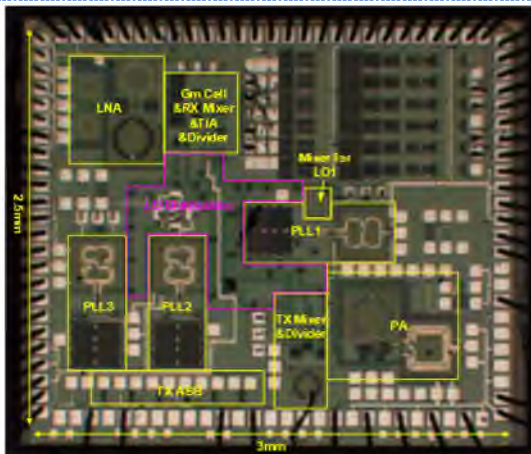
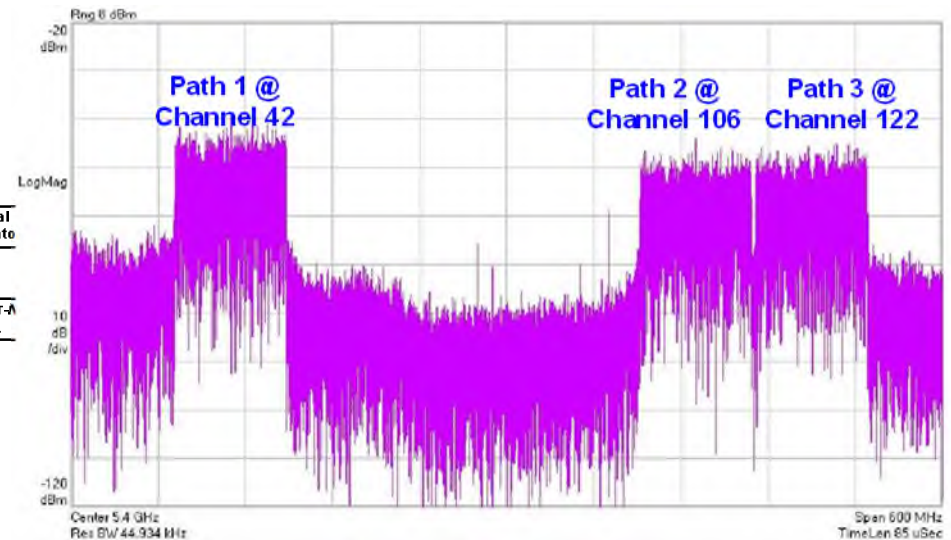
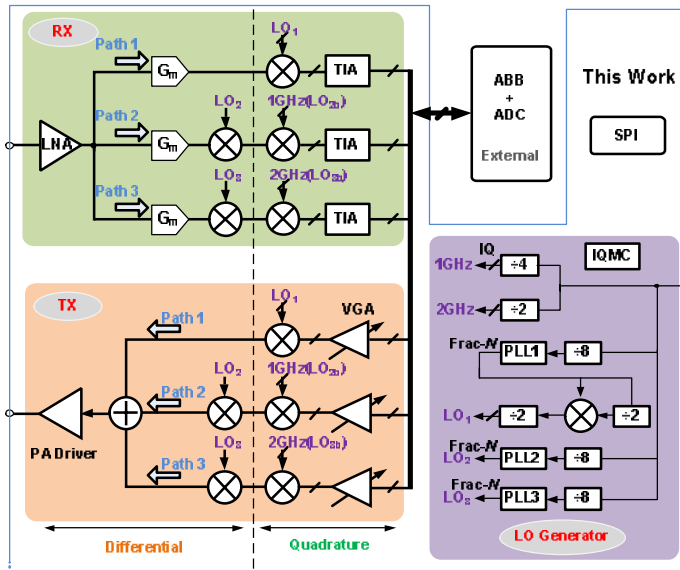
# WiFi-6 vs 5G

COEXIST



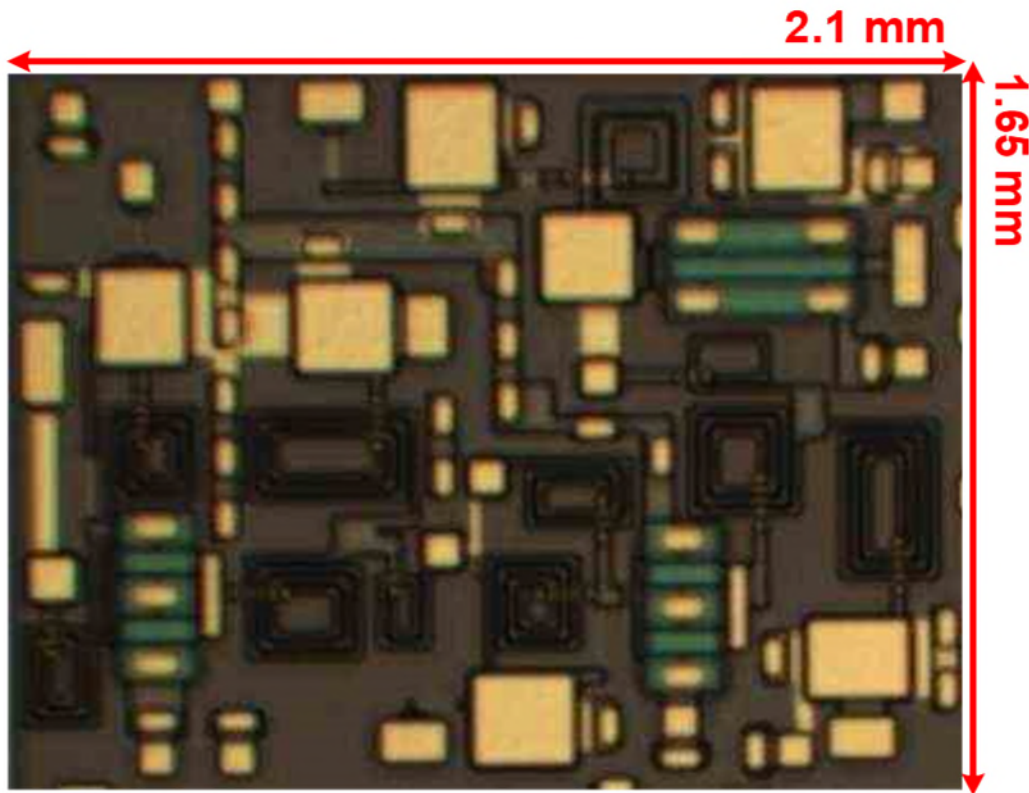


# 2 x 2 MIMO RFIC for Wireless Communication - 3-Carrier Aggregation Transceiver for WiFi-6



1. Proposed transmitter can mitigate cross-talk and VCO pulling
2. Proposed transmitter can support inter-band and intra-band carrier aggregation

**Sub-6GHz 5G GaN PA:  
2.4-6GHz (Fully Int. 2.1mm x 1.65mm)**



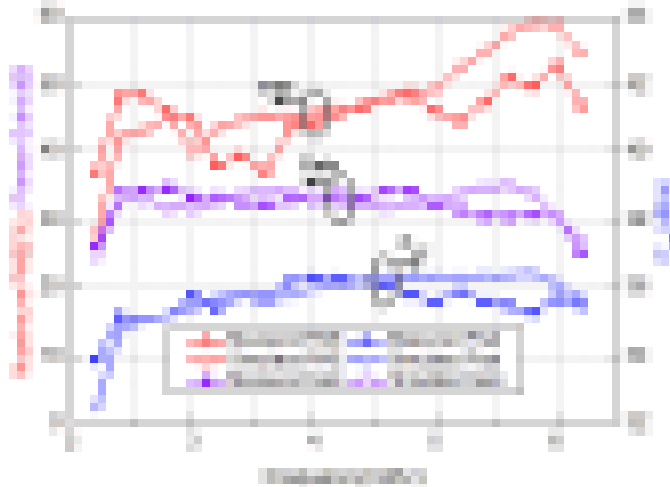
**GaN Die**





# Sub-6GHz 5G GaN PA: 2.4-6GHz (Fully Int. 2.1mm x 1.65mm)

CW performance (**Broadband**)



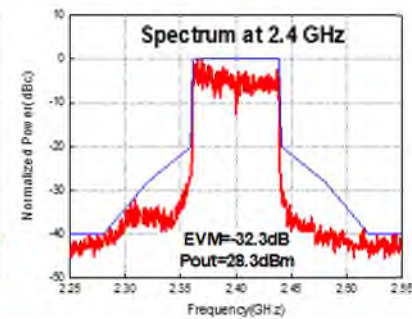
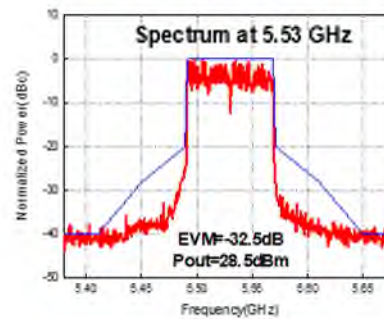
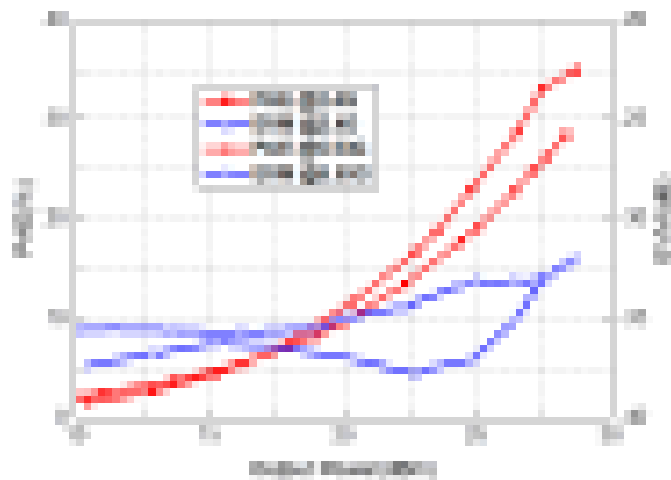
Measured EVM and spectrum using 80-MHz 256-QAM signal

Constellation of 256-QAM with EVM of -32.5dB at 5.53 GHz



	Avg	Ch1
EVM	-32.558 dB	-32.558
EVMPeak	-22.669 dB	-22.669
PilotEVM	-31.496 dB	-31.496
DataEVM	-32.577 dB	-32.577
FreqErr	-1.6740 kHz	***
SymClkErr	0 ppm	***
CPE	0.3718 %rms	***
IQOffset	-46.822 dB	-46.822
IQQuadErr	0.04240 deg	0.04240
IQGainimb	-0.06779 dB	-0.06779
IQTimeSkew	-0.04515 ns	-0.04515
CrossPwr	***	***
SymCorr	0.93609	0.93609
SymTimeAdj	-3.125 %	-3.125
EVM(w/LC)	-32.588 dB	-32.588

PAE and EVM in different power level



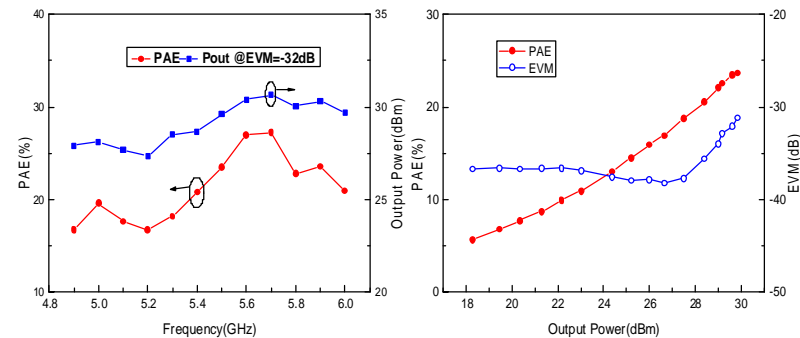
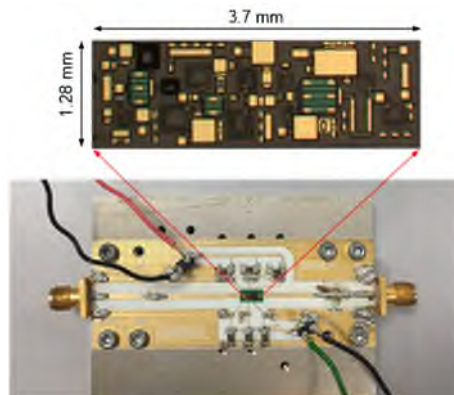
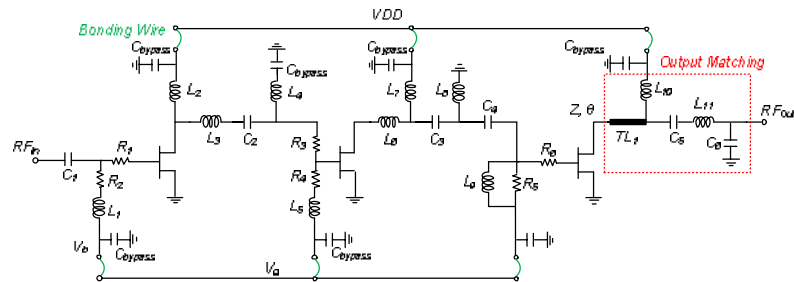
Measured CW performance:

- Frequency: 2.4GHz-6GHz
- Output power: 35.2-36.3dBm
- Efficiency: 38-53%
- Gain: 30.5-34.7dB



# RFIC for Wireless Communication

## - Class-J GaN PA for WiFi-6 (ax)

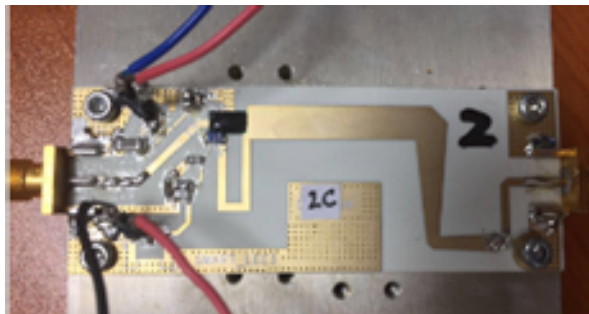
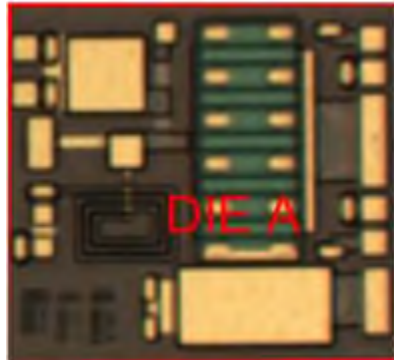


	Proposed PA	SKY85402 (Skyworks)	RFFM8505 (RFMD)	RFPA5026 (Qorvo)
Frequency	4.9-5.9 GHz	5.1-5.8 GHz	4.9-5.85 GHz	4.9-5.9 GHz
Pout @-32dB EVM	<b>23.7-26.3 dBm</b>	22 dBm	19.5 dBm	25 dBm
Efficiency @ -32dB EVM	<b>16.7-27.3%</b>	11.4%	9.5%	9.4 %
Technology	<b>GaN</b>	SiGe	InGaP	InGaP

Performance comparison between the proposed PA and other commercial products

# RFIC for Wireless Communication

## - 1.6-2.7GHz GaN PA for LTE-Advanced

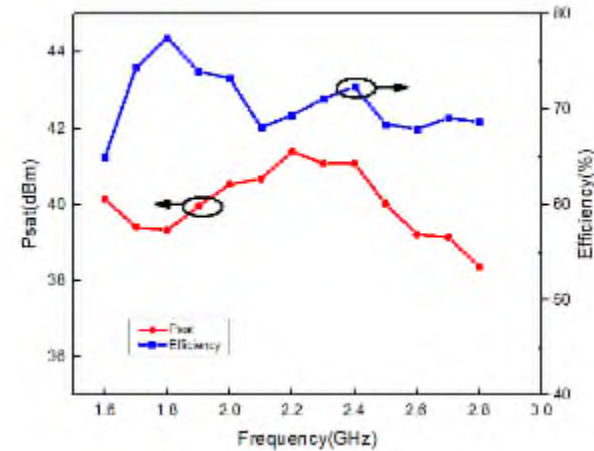


Die and PCB

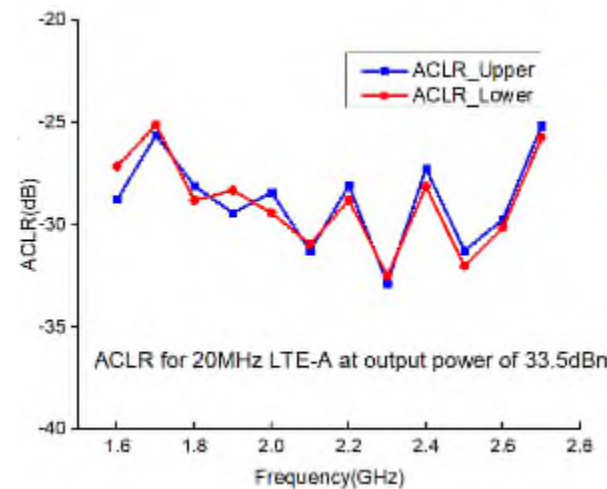
### Measured performance:

- Frequency: 1.6GHz-2.7GHz
- Output power: **39.2-41.1dBm**
- Efficiency: **63-77%**
- Gain: **10-12.3dB (3.5mm<sup>2</sup>)**

### Measured Psat and efficiency

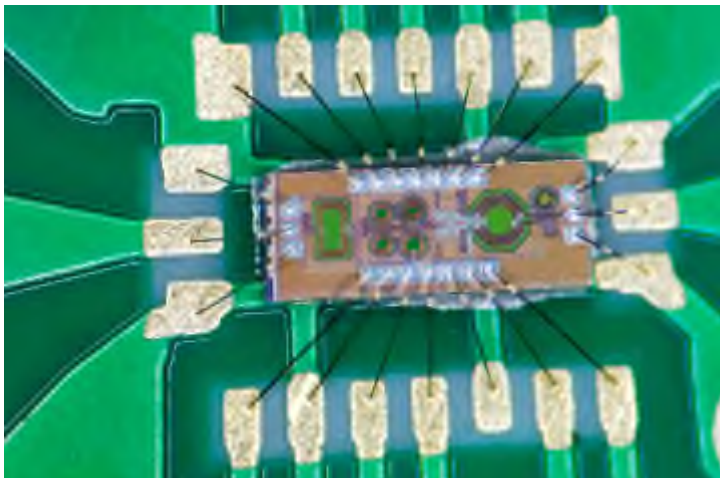
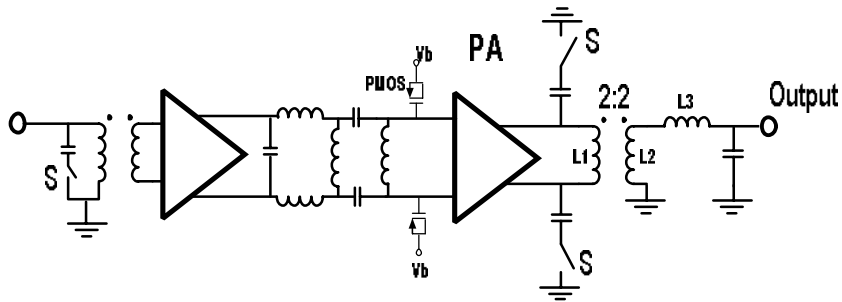


### Measured ACLR for 20MHz LTE-A signal

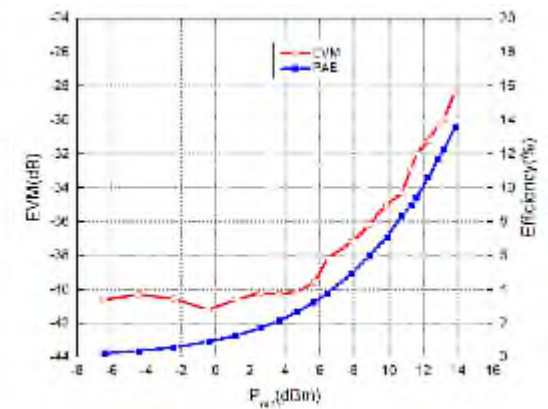
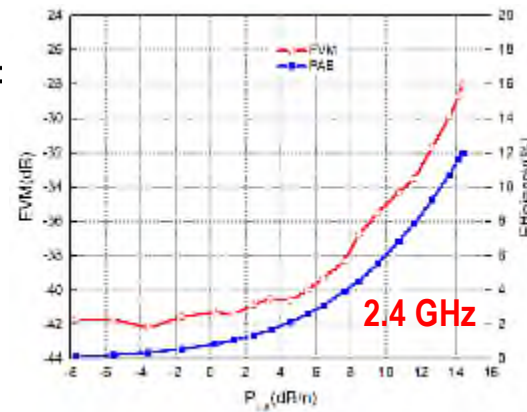


# RFIC for Wireless Communication

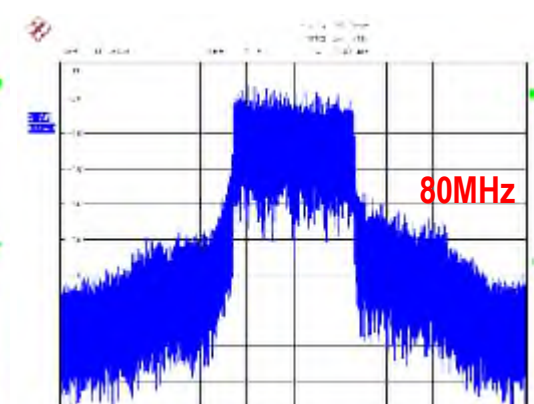
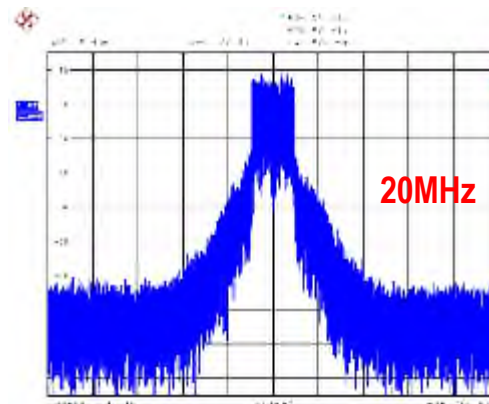
## - CMOS 2.4/4.9-5.9GHz Dual-band PA for Sub-6GHz CA



EVM and Efficiency for **80MHz, 256-QAM** 802.11ax signal



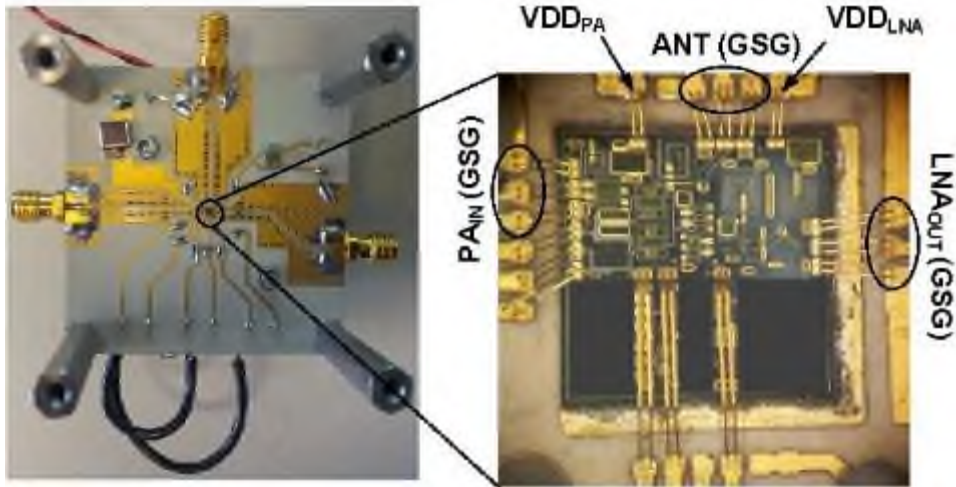
EVM and Efficiency for **20MHz and 80MHz** 802.11ax signal





# RFIC for Wireless Communication

## - GaN RF front-end for 802.11p @ 5.9GHz DSRC



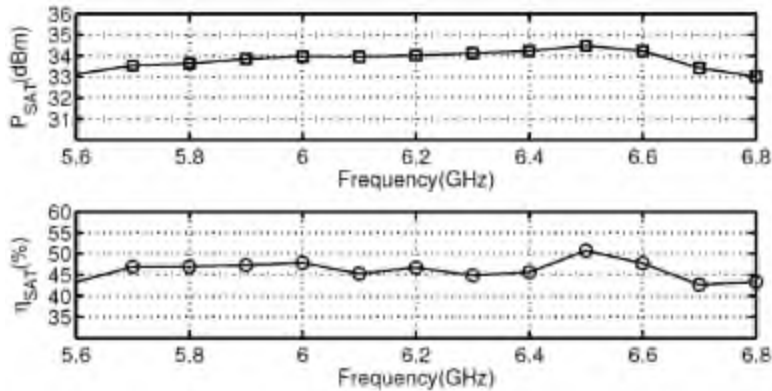
- Fully integrated & energy efficient RF

– PA + LNA + ANT SW

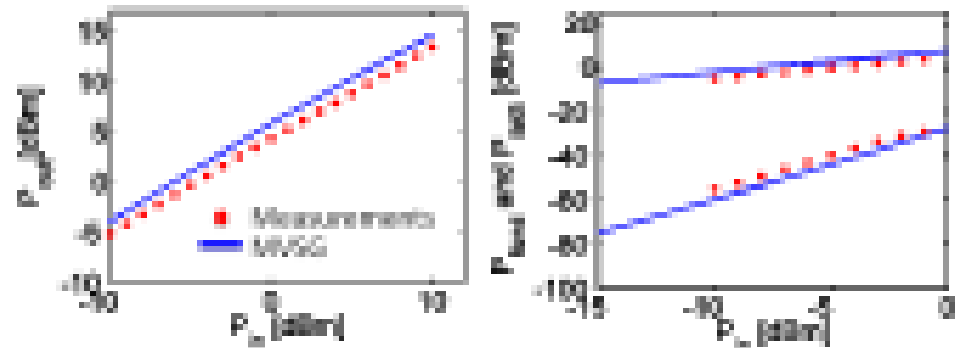
– 2mm x 1.2mm

**Chip-on-Board**

(No external matching)



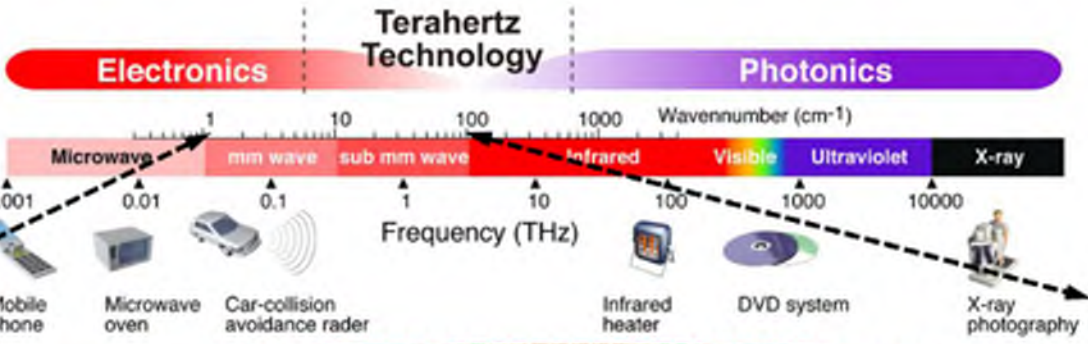
**Tx mode: 50% power efficiency @ 34dBm Psat**



**Rx mode: 22dBm OIP3**

# MM-Wave RFIC

**MM-Wave:**  
10mm - 1mm  
30GHz - 300GHz



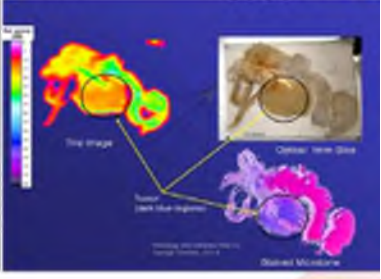
**THz:**  
1mm - 0.1mm  
300GHz - 3000GHz

<b>24GHz</b>	<b>60GHz</b>	<b>70GHz</b>	<b>77/79GHz</b>	<b>80GHz</b>	<b>94GHz</b>	<b>120-220GHz</b>	<b>0.3-3THz</b>
Automotive Radar Wireless Backhaul	WLAN WPAN	Point-to-point Communication Broadband Internet access	Automotive Radar Long Range Short Range	Point-to-point Communication Broadband Internet access	MM-Wave Imaging	MM-Wave Imaging Inter-chip wireless Communication	THz Imaging Radio Astronomy Spectroscopy
22	27 57	64 71	76 77 81	86	94	110 120	220 300 3000



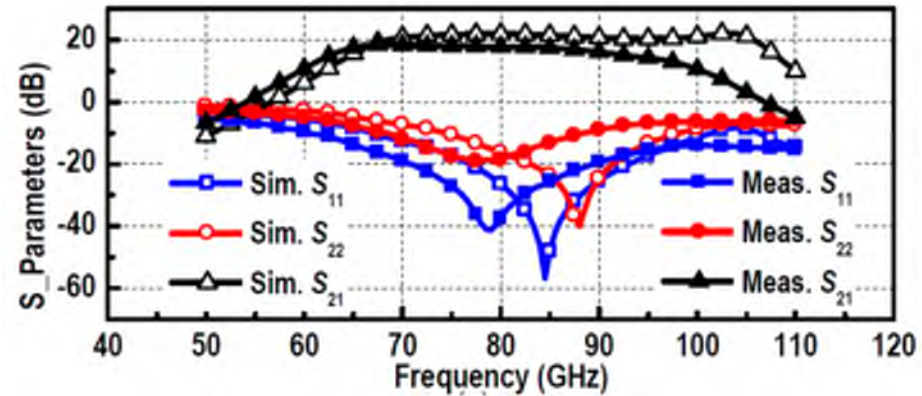
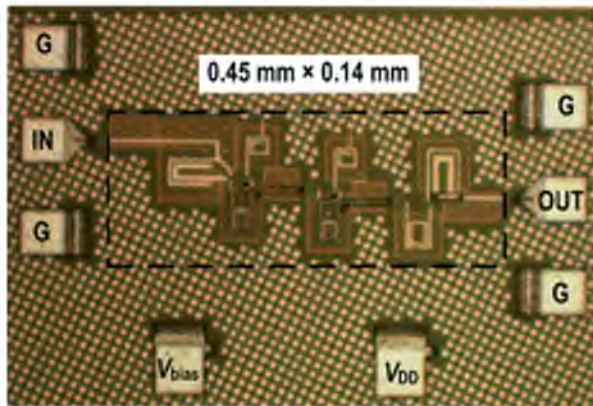
**E-Link Eagle**  
Gigabit Wireless Ethernet Link

- 70/80 GHz system with spectrum efficient 64QAM modulation
- 60nm silicon MMIC technology
- Frequency agile
- Integrated on-chip 12.5mW PA





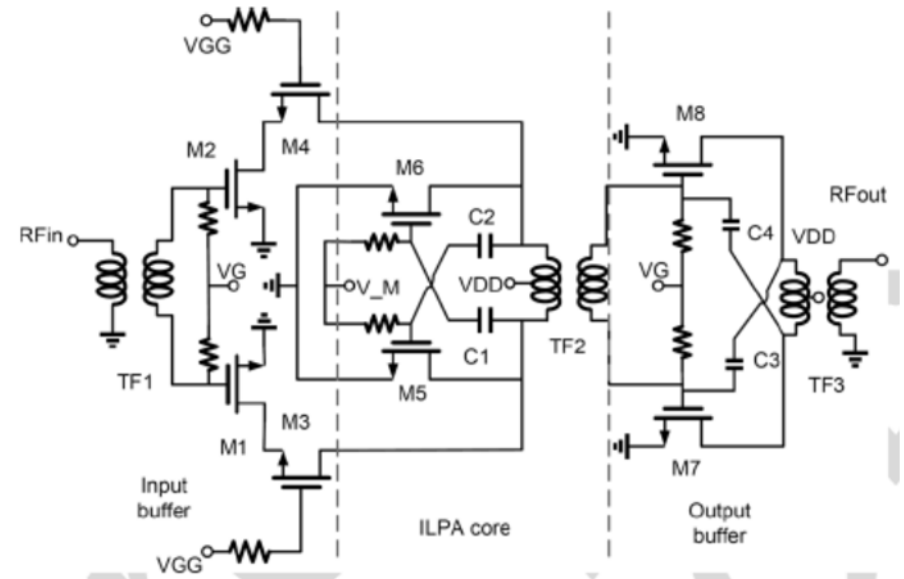
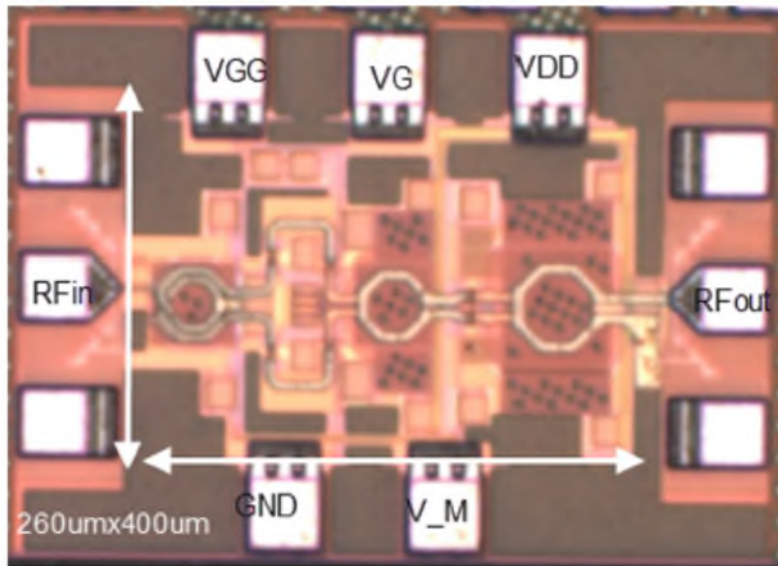
# MM-Wave RFIC: Widest Bandwidth Highest BWER 100GHz LNA



Overcoming Gain Flatness, Wideband Gain Trade-off for MMW Application.

	[4] TMTT 2012	[5] TMTT 2015	[6] ISSCC 2010	This Work
Technology	45nm SOI CMOS	28nm CMOS	65nm CMOS	<b>65nm CMOS</b>
Topology *	3-stage CS	2-stage Cas.	3-stage Cas.	<b>3-stage Cas.</b>
Power Gain [dB]	10.7@95GHz	13.8@66GHz	17.5@77GHz	<b>18.5@67GHz</b>
BW ** [GHz]	18	18	17 #	<b>30</b>
NF <sub>min</sub> [dB]	6.0	4.0	7.4	<b>6.1</b>
$P_{1dB}$ ## [dBm]	N/A	-12.5	-22.0	<b>-11.8</b>
$P_{DC}$ [mW]	52	24	30	<b>27.4</b>
Size [mm <sup>2</sup> ]	0.32	0.38	0.37	<b>0.24</b>
FoM † [GHz/mW]	0.40	2.43	0.95	<b>3.00</b>

# MM-Wave RFIC: 50-59GHz High Gain Power Amplifier



This work demonstrates an ILPA with largest injection locking bandwidth. The fabricated PA has achieved a injection locking range from 50 GHz to 59 GHz. Maximum output power of 11.39 dBm has been obtained while the highest PAE is 16.1 %. Moreover, the chip size is 260 μm x 400 μm excluding pads.

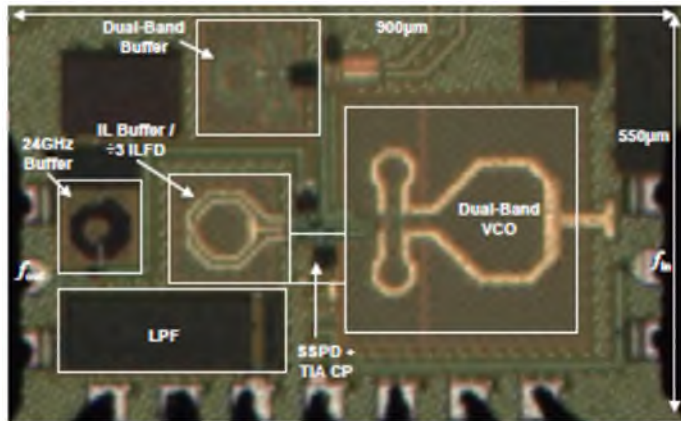
MM-WAVE CMOS HIGH EFFICIENCY PA

Technology	Topology	Freq(GHz)	Max Gain (dB)	Pmax(dBm)	PAE(%)	Area(mm <sup>2</sup> )
CMOS 65nm -This work	Buffered Input&Output	50-59	37.8	11.39	16.1	0.104
CMOS 65nm [3]	2 to 1 transformer	52.5-54.5	29	9.6	17.3	0.1
CMOS 65nm [1]	ZVS	57-65	5	-1.5	20*	NA

\*Drain efficiency



# MM-Wave RFIC: 24/77GHz Dual-Band vehicle FMCW Radar



← Best phase noise  
← Best power efficiency

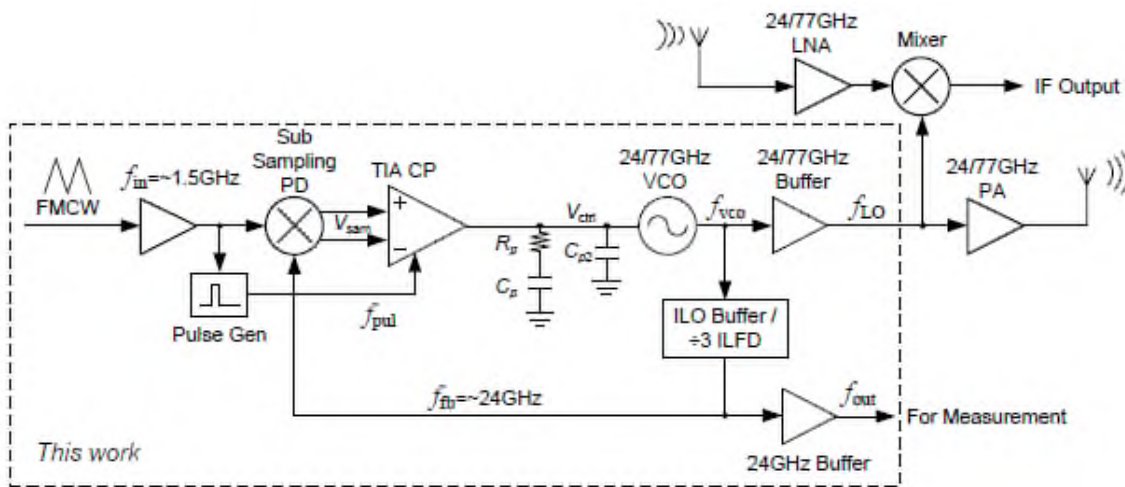
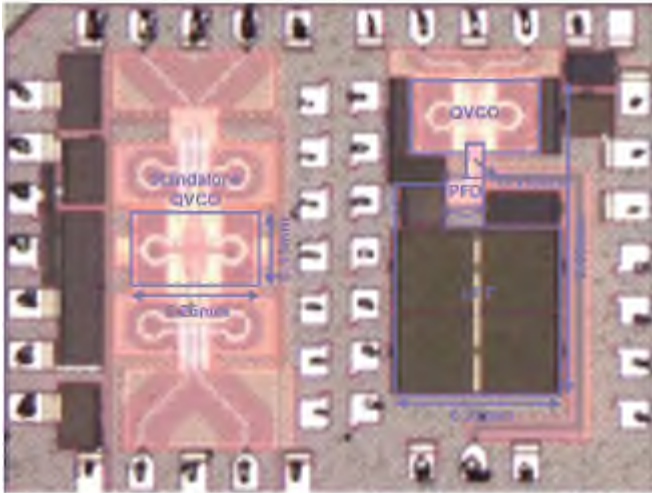


Fig. 1. Automotive radar applications

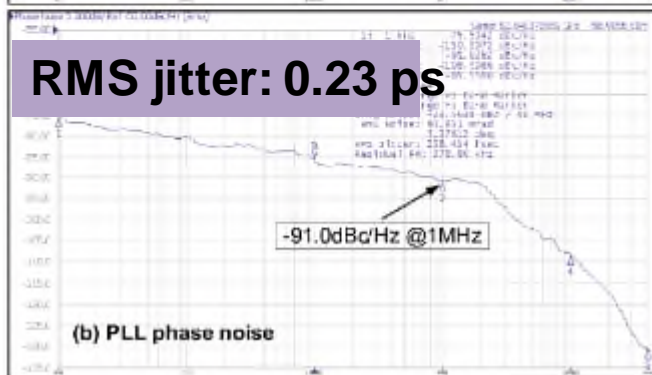
# MM-Wave RFIC: 57.9-68.3GHz PLL



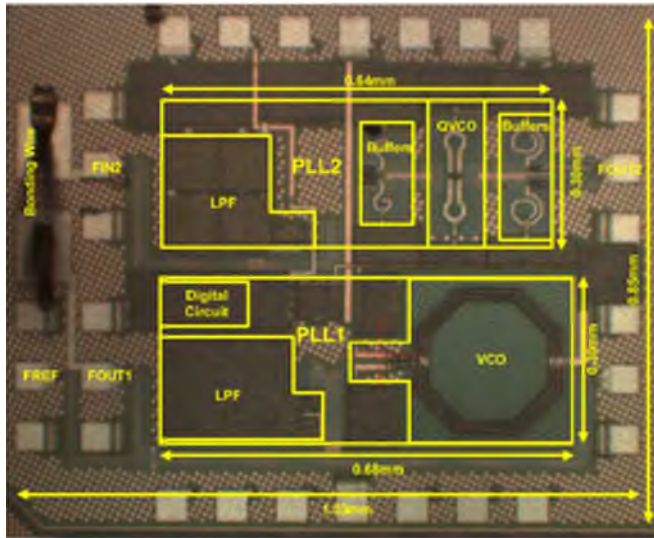
Yi Xiang, Boon Chirn Chye, et al. (ISSCC 2013)  
Fast settling due to high reference freq., Ultra low  
phase noise (low jitter), energy efficiency.



**RMS jitter: 0.23 ps**

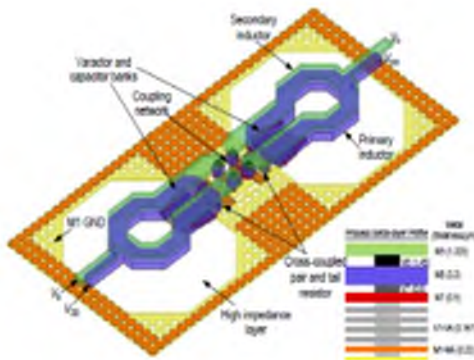


# MM-Wave RFIC: World First 100GHz Fractional-N PLL in CMOS



Ultra-compact PLL  
Overcoming frequency resolution, fast settling, signal purity trade-off.

Ref.	Tech. (nm)	Operating Range (GHz)	P.N.@1MHz /10MHz (dBc/Hz)	FOM <sub>T</sub> @1MHz /10MHz (dBc/Hz)	FOM <sub>τ</sub> @1MHz /10MHz (dBc/Hz)	Output Phase	Power (mW)
[2]	65 CMOS	98~103.3 (5.2%)	-75 <sup>(3)</sup> /-112.1	-164.49/ -181.59	-158.81 /-175.91	Differential	12~21
		91.7~95.5 (4.1%)	-80 <sup>(3)</sup> /-118.8	-162.79/ -181.59	-155.04 /-173.84	Eight Phases	48~85
[3]	65 CMOS	100~110 (9.5%)	-92.83 /-100 <sup>(3)</sup>	-175.9 /-163.1	-175.5 /-162.7	Quadrature	54
<b>This work</b>	<b>65 CMOS</b>	<b>93.24~105.02 (11.9%)</b>	<b>-93.80 /-112.67</b>	<b>-178.6 /-177.5</b>	<b>-180.2 /-179.0</b>	<b>Quadrature</b>	<b>30</b>



Ref.	Tech. (nm)	$f_{ref}$ (MHz)	Operating Range (GHz)	P.N.@1MHz /10MHz (dBc/Hz)	Reference Spur (dBc)	Resolution (MHz)	Output Phase	Architecture	Power (mW)
[4]	65 CMOS	371.5 ~377.0	95.1~96.5 (1.5%)	-76 /-93 <sup>(3)</sup>	-51.8	$f_{REF}$	Differential	Integer-N	43.7
[5]	65 CMOS	185.7 ~211.9	96.8~108.5 (11.4%)	-88 /-105 <sup>(3)</sup>	-40	$f_{REF}$	Differential	Integer-N + Push-Push	14.1
[6]	65 CMOS	402.6 ~408.5	103.058~104.58 (1.5%)	-80.41 /-101.08	-63.8	$f_{REF}$	Differential	Integer-N	63
<b>This work</b>	<b>65 CMOS</b>	<b>100</b>	<b>93.4~104.8 (11.5%)</b>	<b>-86.07 /-108.75 /-103.53<sup>(4)</sup></b>	<b>-44.69</b>	<b>0.000036<math>f_{REF}</math><sup>(4)</sup></b>	<b>Quadrature</b>	<b>Frac-N + Sub-Sampling</b>	<b>57</b>

(1)  $FOM = P.N. - 20\log(f_0/\Delta f) + 10\log(\text{Power}/1\text{mW})$ .

(2)  $FOM_{\tau} = FOM - 20\log(\% \text{ of Operating Range}/10\%)$ .

(3) Estimated from figures.

(4) PLL is in fractional-N mode.



# MM-Wave RFIC: 160GHz 3.7mW Output Power Signal Source

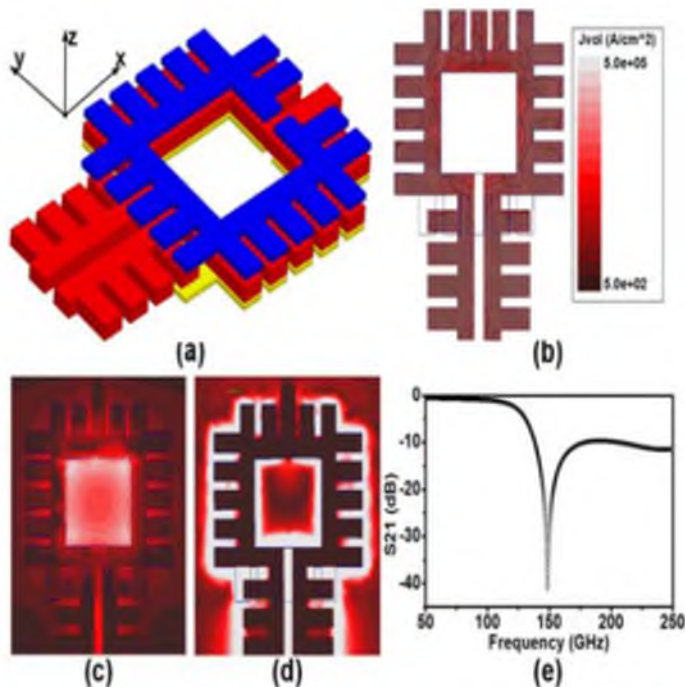


Fig. 3 (a) The proposed surface-wave resonator, the simulated (b) surface current distribution, (c) magnetic field distribution, (d)  $E$ -field distribution, and (e)  $S_{21}$  of surface-wave resonator.

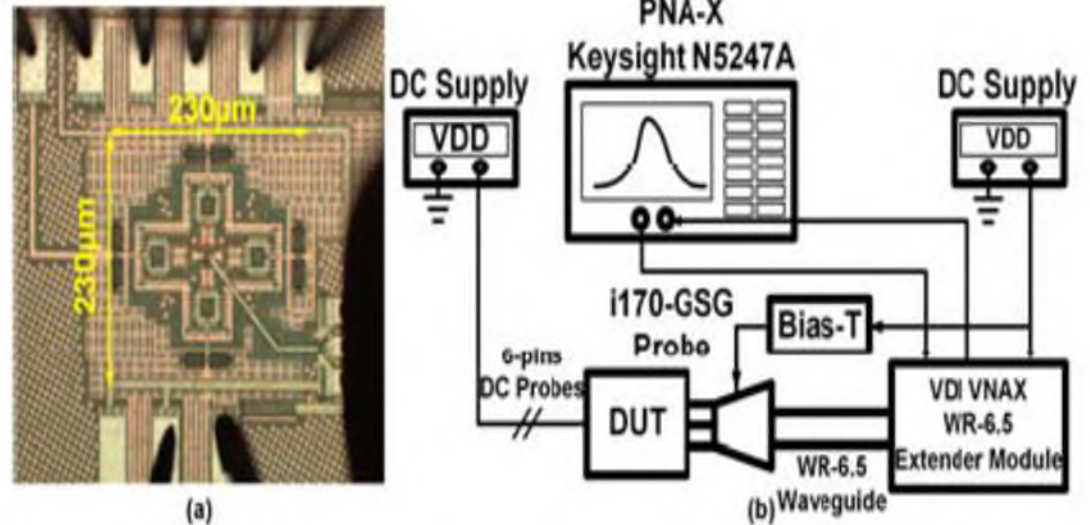


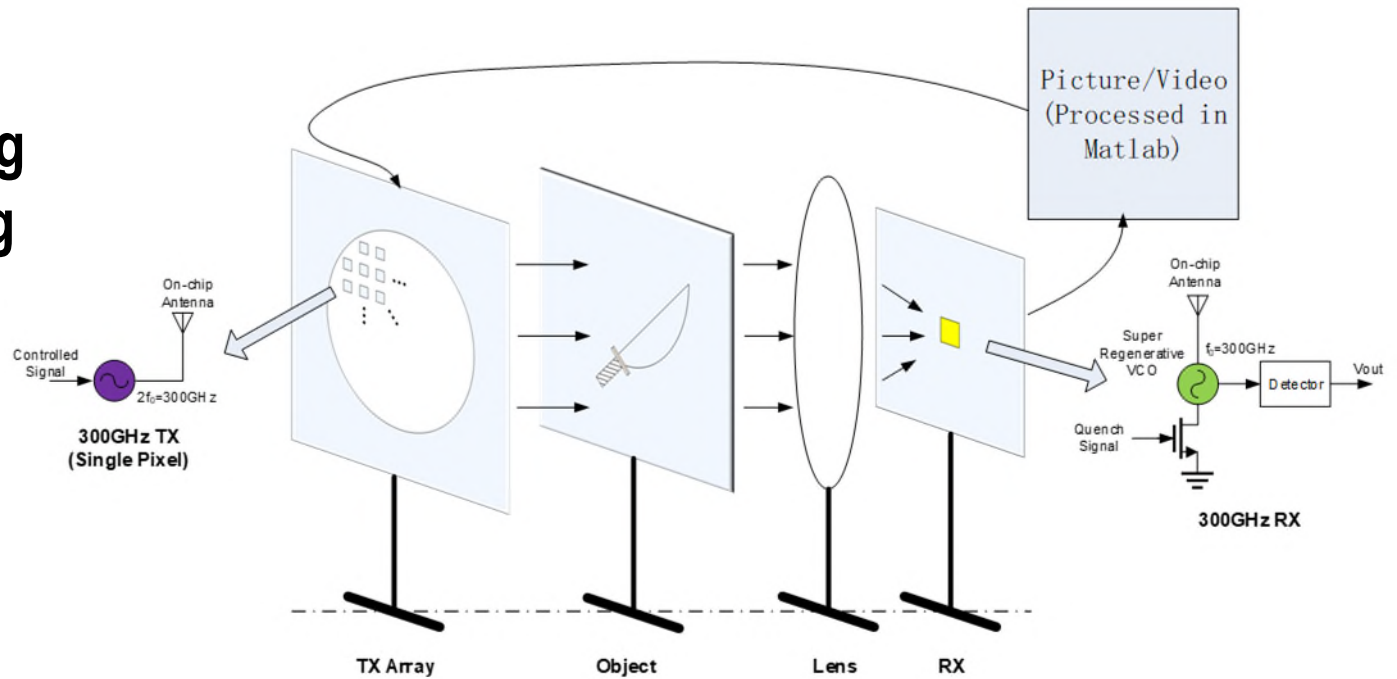
Fig. 5 (a) Die photo, and (b) the 110-170 GHz measurement setup

A 4-way surface-wave signal source is designed in 65nm CMOS at 160 GHz. Low loss as signal source for sub-THz communication. Measurement results 3.7 mW output power 5.5% DC-RF efficiency, 6.3% FTR and -105 dBc/Hz phase noise at 10 MHz offset, leading state-of-the-art FOM of -171 dBc/Hz and FOMT of -172.7 dBc/Hz in literature.

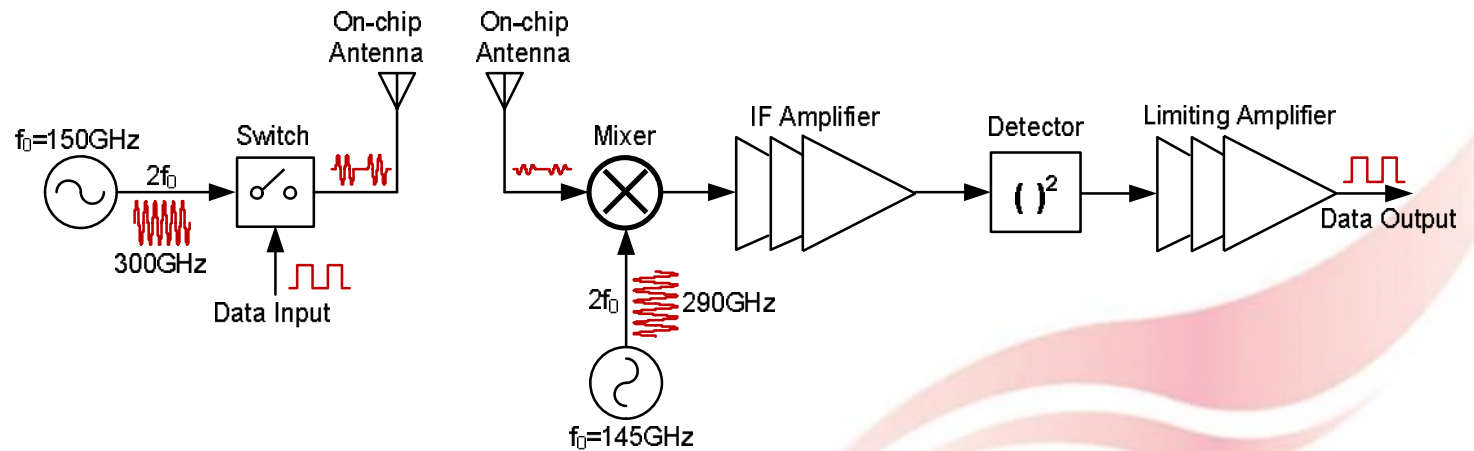


# THz RFIC: 300GHz Power Source and Imaging Sensor

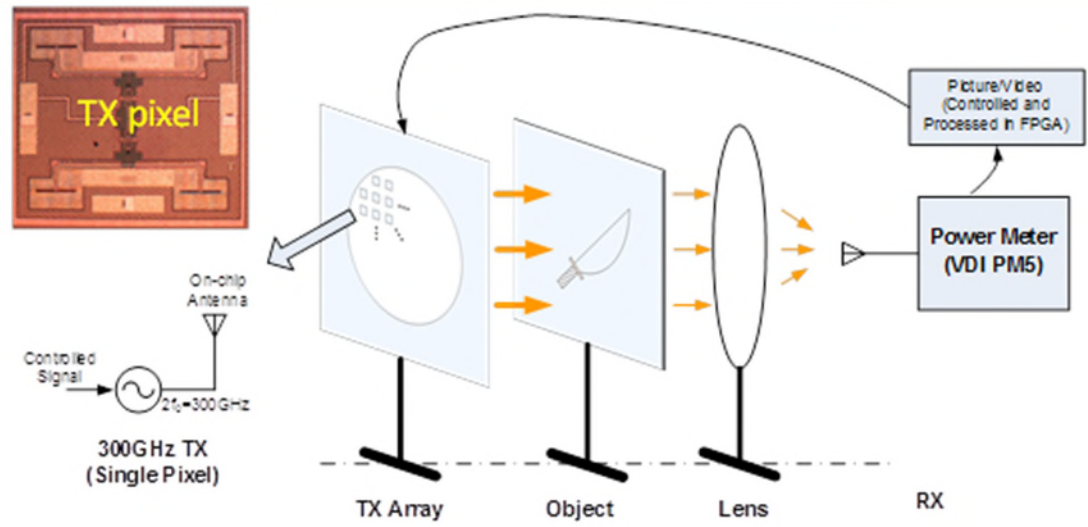
## 300 GHz Imaging Video Streaming



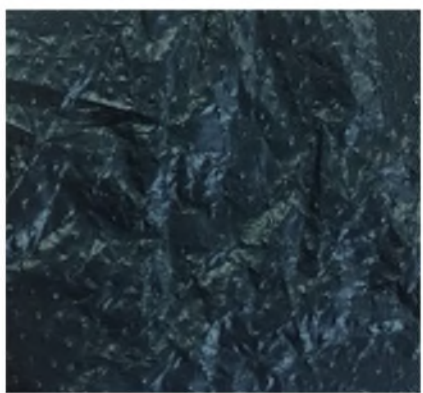
## THz Transceiver 9Gbps Communication



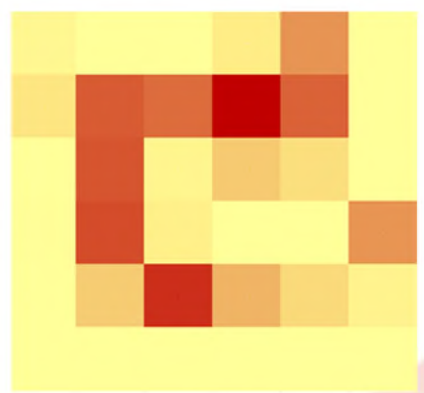
# THz RFIC: 300GHz Power Source and Imaging Sensor



**Metal letter "C" is inside a black non-transparent plastic bag.**



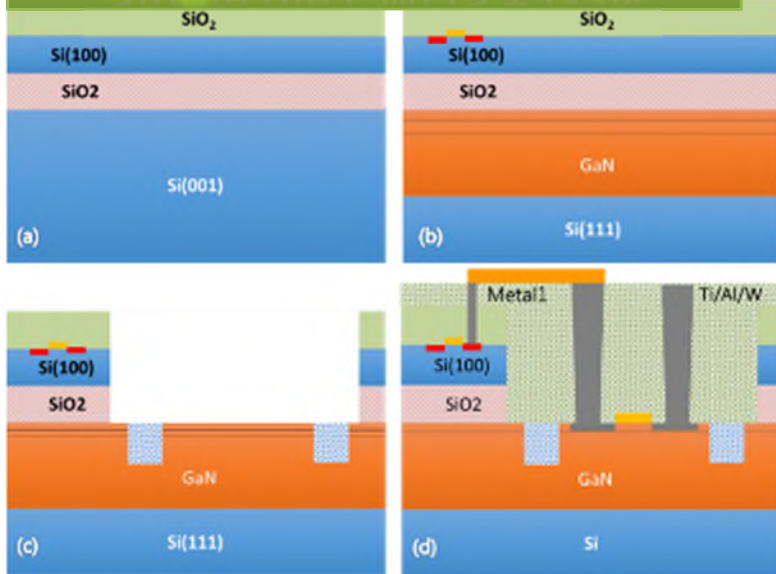
(a) Visible image



(b) mmW image

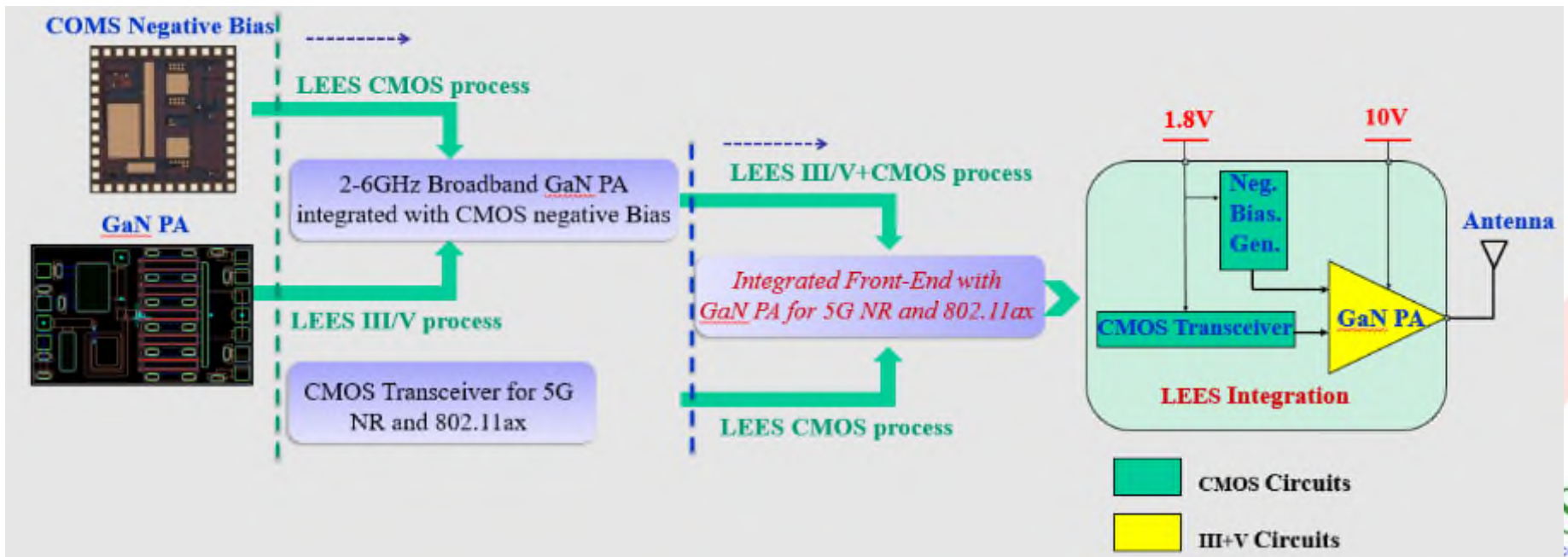
# Current Work: CMOS + GaN Integrated in a Single Chip

## Single die CMOS + GaN



## Research Direction:

- 5-6GHz CMOS transceiver for 802.11ax WLAN
- Sub-6GHz CMOS transceiver for 5G NR
- 2-6GHz Broadband GaN Power Amplifier
- Integrated CMOS transceiver and GaN Power Amplifier in a single chip





**Thank you for your time and effort  
to understand our work.**

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patents/publications/books

